

CHIP MANUFACTURING METHOD

ABSTRACT

A chip manufacturing method includes a modified layer forming step of forming a modified layer and a crack by applying, along planned dividing lines, a first laser beam having a wavelength transmitted through a substrate of a wafer including the substrate and a laminate in a state in which the back surface side of the substrate is exposed and a condensing point of the first laser beam is positioned within the substrate from the back surface side of the substrate, a grinding step of thinning the wafer to a predetermined thickness by grinding the back surface side of the substrate exposed in the modified layer forming step, and a laser-processed groove forming step of forming a laser-processed groove in the laminate by applying, along the planned dividing lines, a second laser beam having a wavelength absorbed by the substrate.

[Fig. 2]